



Appendix 3 Product End-of-Life Disassembly instructions

Product Identification:

Marketing Name / Model	Description
HP Compaq Business Desktop dc7100 Series - CMT	HP business desktop PC – Convertible Minitower Chassis

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Qty items in product.
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 square cm	1 PCS
Batteries	All types including standard alkaline and lithium coin or button style batteries	1 PCS
Mercury containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 square cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB / PCT)		
Electrolytic Capacitors / Condensers greater than 2.5 cm in diameter or ht		
External electrical cables and cords	PSU cables, IDE cables, SATA cables.	
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		



2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Flat blade screwdriver	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

SYSTEM BOARD	
1	To remove the access panel (see Figure 1 below): a) Lift up on the access panel handle and slide the access panel back about 1 inch (2.5 cm). b) Lift the access panel off the unit.
2	Remove all expansion cards, cables, and any other devices from the system board.
3	To remove the heatsink (see Figure 2 below): a) Disconnect the heatsink control cable from the system board. b) Unscrew the four captive screws that secure the heatsink to the system board. c) Remove the heatsink from atop the processor.
4	To remove the system board (see Figure 3 below): a) Compress the system board tray handle to release the latch and slide the system board tray towards the front of the computer to free it from the back of the chassis. b) Lift the system board out of the chassis.
BATTERY	
	Locate the battery and battery holder on the system board. Depending on the type of battery holder on the system board, complete the following instructions to remove the battery:
	TYPE 1 BATTERY HOLDER (see Figure 4 below)
	Lift the battery out of the holder.
	TYPE 2 BATTERY HOLDER (see Figure 5 below)
	To release the battery from its holder, squeeze the metal clamp that extends above one edge of the battery. When the battery pops up, lift it out.

3.2 ILLUSTRATIONS

FIGURE 1: Removing the access panel

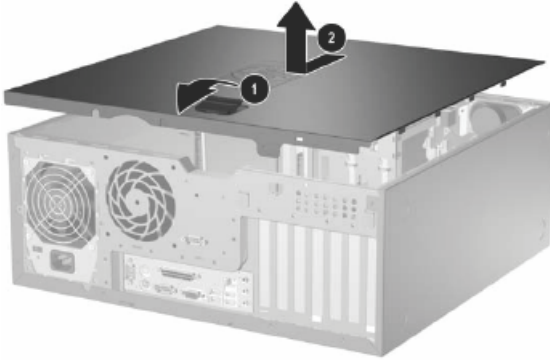


FIGURE 2: Removing the heatsink

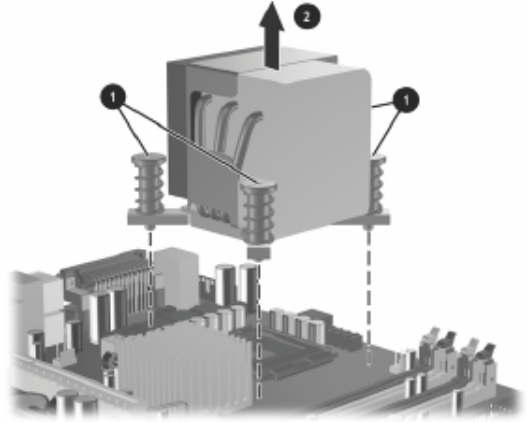


FIGURE 3: Removing the system board

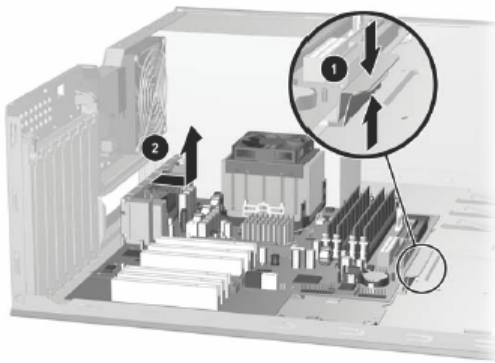


FIGURE 4: Type 1 battery holder

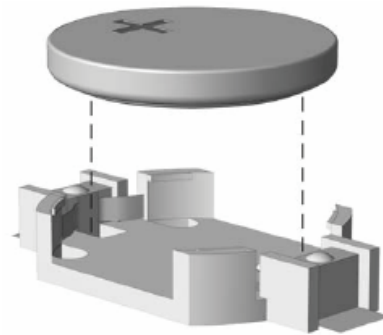


FIGURE 5: Type 2 battery holder

